



Solid State Devices, Inc.

14701 Firestone Blvd * La Mirada, Ca 90638
Phone: (562) 404-4474 * Fax: (562) 404-1773
ssdi@ssdi-power.com * www.ssdi-power.com

Designer's Data Sheet

Part Number/Ordering Information ^{1/}

SDR52



Screening ^{2/}

— = Not Screened
TX = TX Level
TXV = TXV
S = S Level

Package Type

— = Axial
SMS = Surface Mount Square
Tab

Voltage/Family

6 = 600V
7 = 700V
8 = 800V
9 = 900V

SDR526 thru SDR529
SDR526SMS thru SDR529SMS

3 AMPS
600 – 900 VOLTS
35 nsec
HYPER FAST
RECTIFIER

FEATURES:

- Hyper Fast Recovery: 35 nsec maximum
- PIV up to 900 Volts
- Avalanche Breakdown
- Hermetically Sealed
- For High Efficiency High Voltage Applications
- Single Chip Construction
- Metallurgically Bonded
- TX, TXV, and Space Level Screening Available^{2/}

MAXIMUM RATINGS		Symbol	Value	Units
Peak Repetitive Reverse Voltage and DC Blocking Voltage @ 50µA	SDR526 SDR527 SDR528 SDR529	V_{RRM} V_{RWM} V_R	600 700 800 900	Volts
Average Rectified Forward Current (Resistive Load, 60 Hz, Sine Wave, $T_A=25^\circ C$)	I_O		3	Amps
Peak Surge Current (8.3 ms Pulse, Half Sine Wave, Superimposed on I_O , allow junction to reach equilibrium between pulses, $T_A=25^\circ C$)	I_{FSM}		60	Amps
Operating and Storage Temperature	T_{OP} & T_{stg}		-65 to +175	°C
Maximum Thermal Resistance Junction to Lead, L = 0.125" (Axial Lead) Junction to End Tab (Surface Mount)	$R_{\theta JL}$ $R_{\theta JE}$		20 10	°C/W

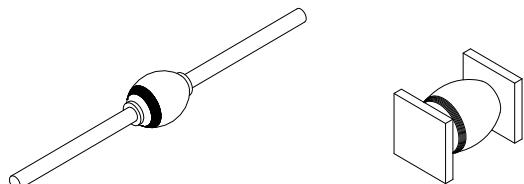
Notes:

1/ For Ordering Information, Price, Operating Curves, and Availability- Contact Factory.

2/ Screening Based on MIL-PRF-19500. Screening Flow Available on Request.

Axial

Surface Mount
Square Tab (SMS)

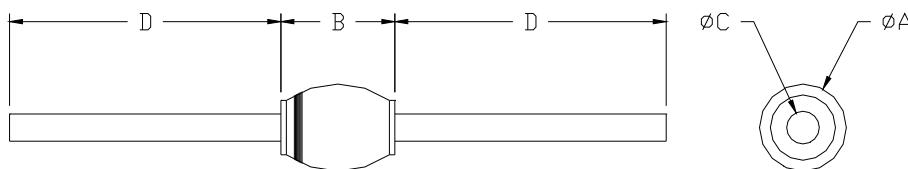


NOTE: All specifications are subject to change without notification.
SCD's for these devices should be reviewed by SSDI prior to release.

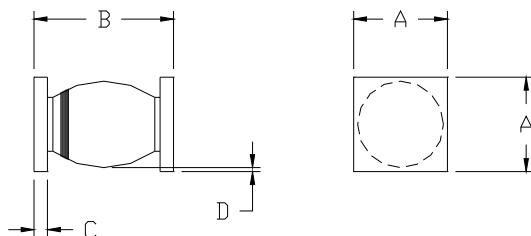
DATA SHEET #: RC0049F

DOC

ELECTRICAL CHARACTERISTICS		Symbol	Min	Max	Unit
Instantaneous Forward Voltage Drop ($I_F = 3 \text{ A}_{DC}$, 300 - 500 μsec Pulse)	$T_A = 25^\circ\text{C}$ $T_A = -55^\circ\text{C}$	V_{F1} V_{F2}	—	2.50 2.50	Volts Volts
Reverse Leakage Current (Rated V_R , 300 μsec minimum pulse)	$T_A = 25^\circ\text{C}$ $T_A = 100^\circ\text{C}$	I_{R1} I_{R2}	—	50 250	μA μA
Junction Capacitance ($V_R = 10 \text{ V}_{DC}$, $T_A = 25^\circ\text{C}$, $f = 1 \text{ MHz}$)		C_J	—	50	pF
Reverse Recovery Time ($I_F = 500 \text{ mA}$, $I_R = 1 \text{ A}$, $I_{RR} = 250 \text{ mA}$, $T_A = 25^\circ\text{C}$)		t_{rr}	—	35	ns

Case Outline: (Axial)


DIM	MIN	MAX
A	0.140"	0.180"
B	0.170"	0.230"
C	0.046"	0.053"
D	1.00"	—

Case Outline: (SMS)


DIM	MIN	MAX
A	0.170"	0.180"
B	0.220"	0.280"
C	0.020"	0.030"
D	0.002"	—

Note: Dimensions prior to soldering.

NOTES:

Consult manufacturing for operating curves.